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(12) **United States Design Patent**  
**Hirata et al.**

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(54) **PACKAGED SEMICONDUCTOR MODULE**

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(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**

USPC ..... D13/182

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H01L 21/4846; H01L 21/4871; H01L  
21/67144; H01L 2224/42; H01L 2224/43;  
H01L 2224/01; H01L 2224/08055; H01L  
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H01L 23/49805; H01L 23/49811; H01L  
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2924/181; H01L 2924/1811; H01L

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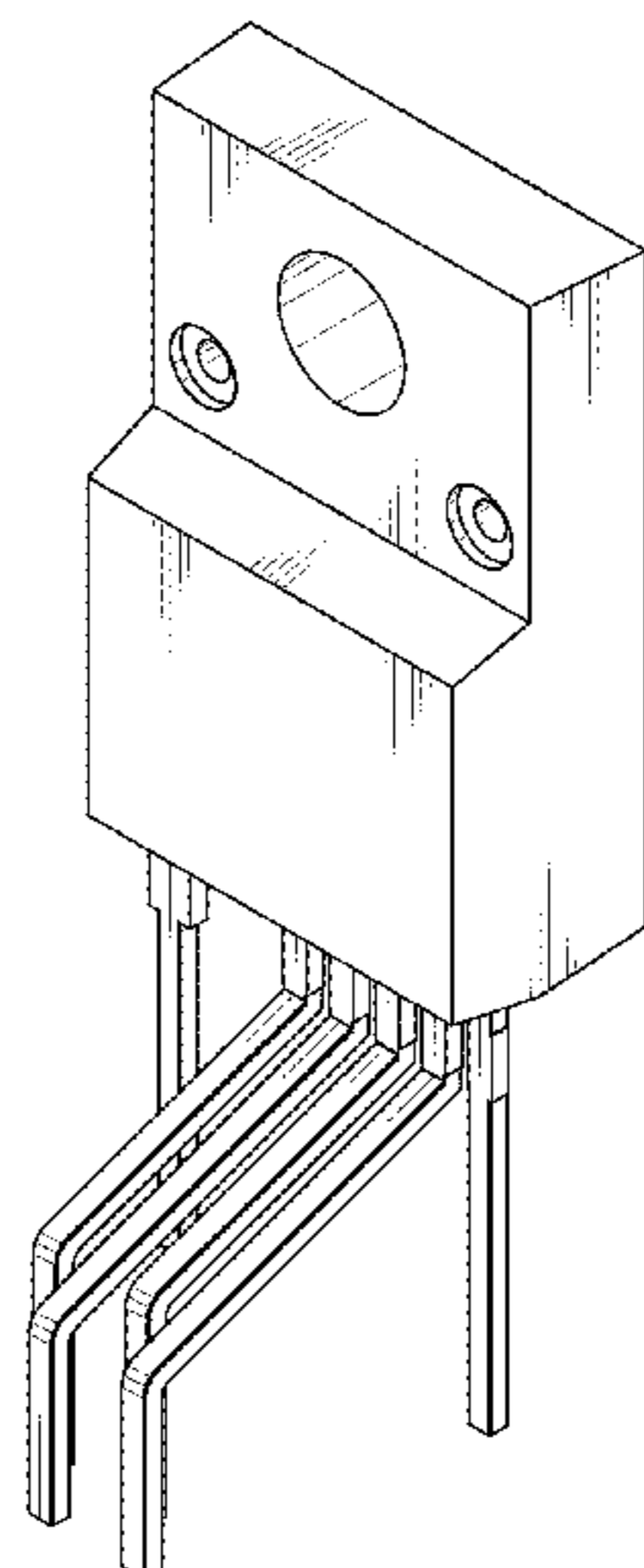
(57) **CLAIM**

The ornamental design for a packaged semiconductor module, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a packaged semiconductor module showing our new design;  
FIG. 2 is a front view thereof;  
FIG. 3 is a rear view thereof;  
FIG. 4 is a top plan view thereof;  
FIG. 5 is a bottom plan view thereof;  
FIG. 6 is a right side view thereof;  
FIG. 7 is a left side view thereof;  
FIG. 8 is a cross sectional view taken along lines 8-8 in FIG. 2; and,  
FIG. 9 is a cross sectional view taken along lines 9-9 in FIG. 2.

**1 Claim, 7 Drawing Sheets**



(58) **Field of Classification Search**  
 CPC ..... 2924/1815; H01L 2924/19042; H01L  
 2924/1905  
 See application file for complete search history.

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Fig. 1

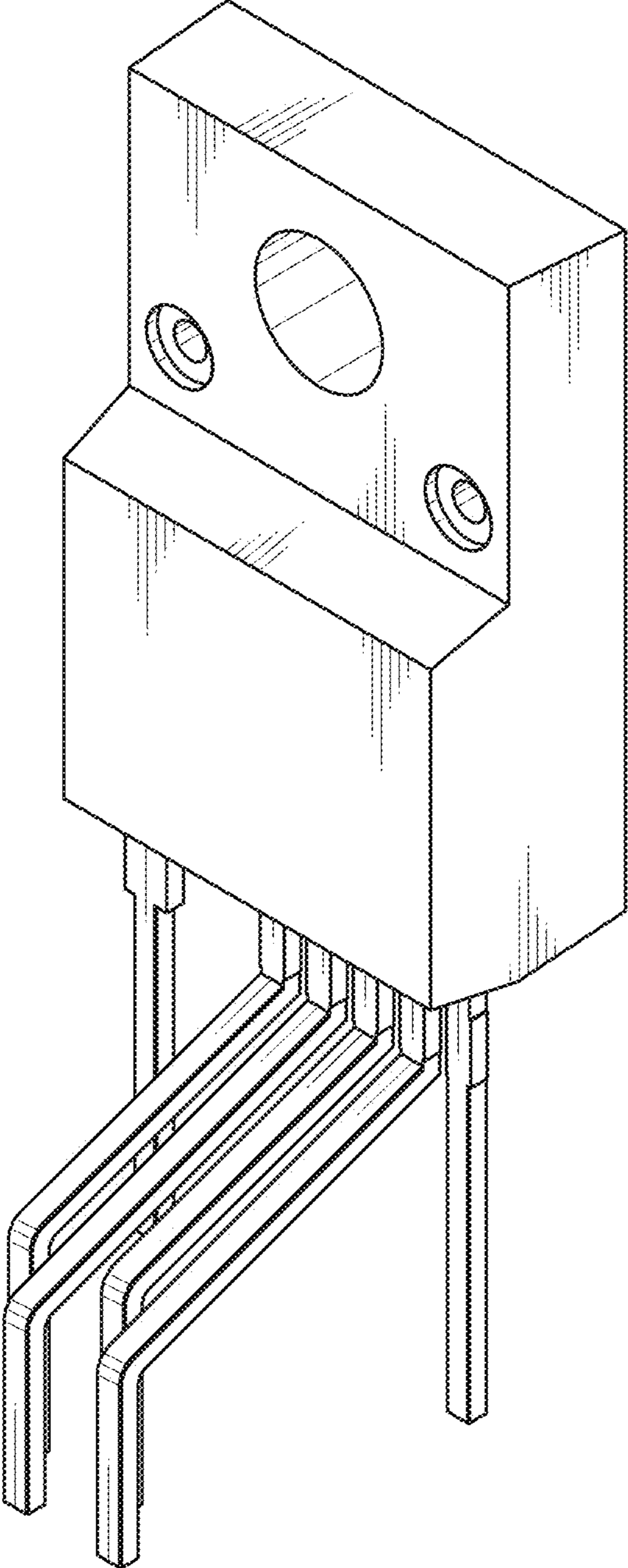


Fig. 2

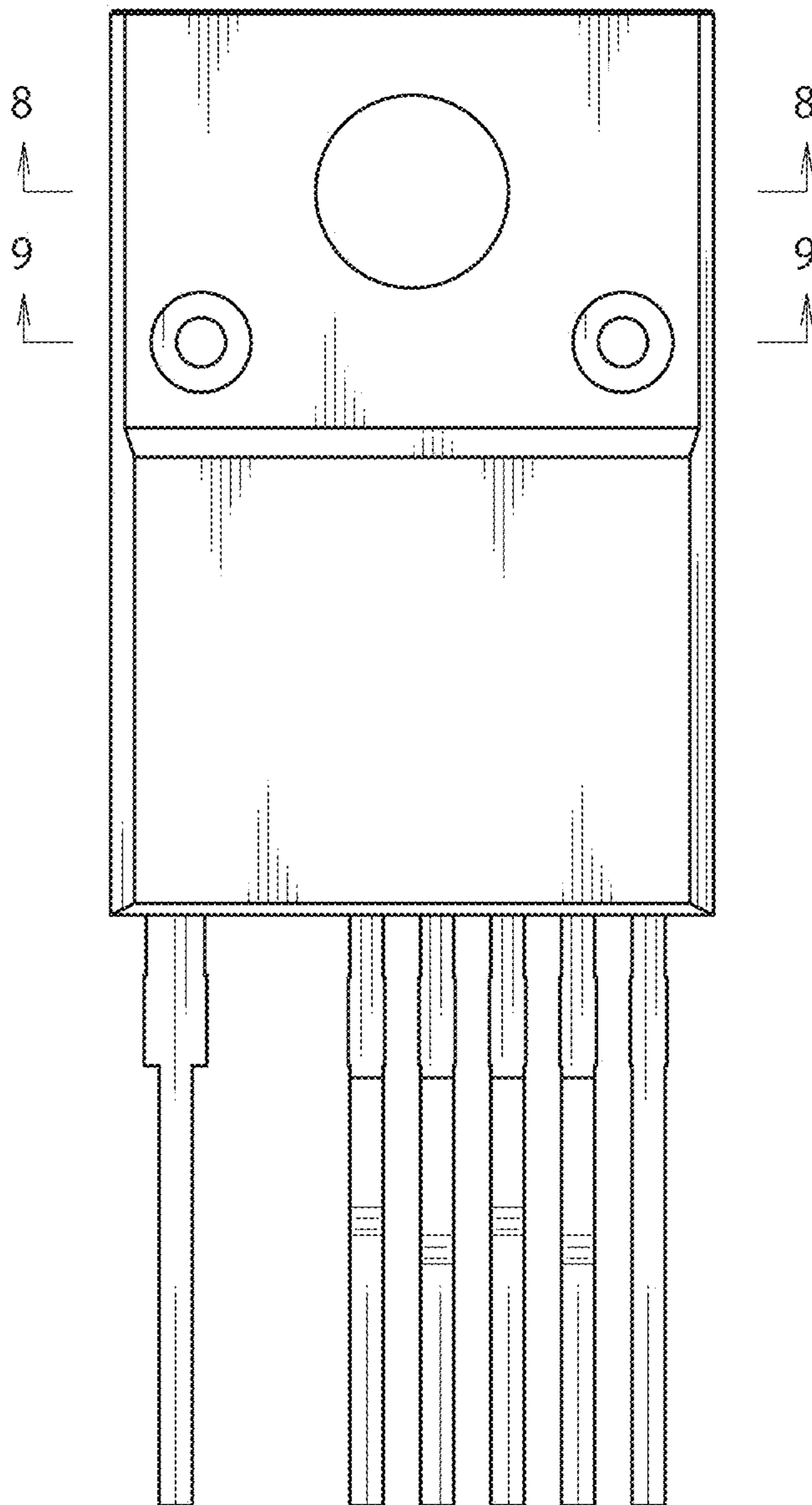


Fig. 3

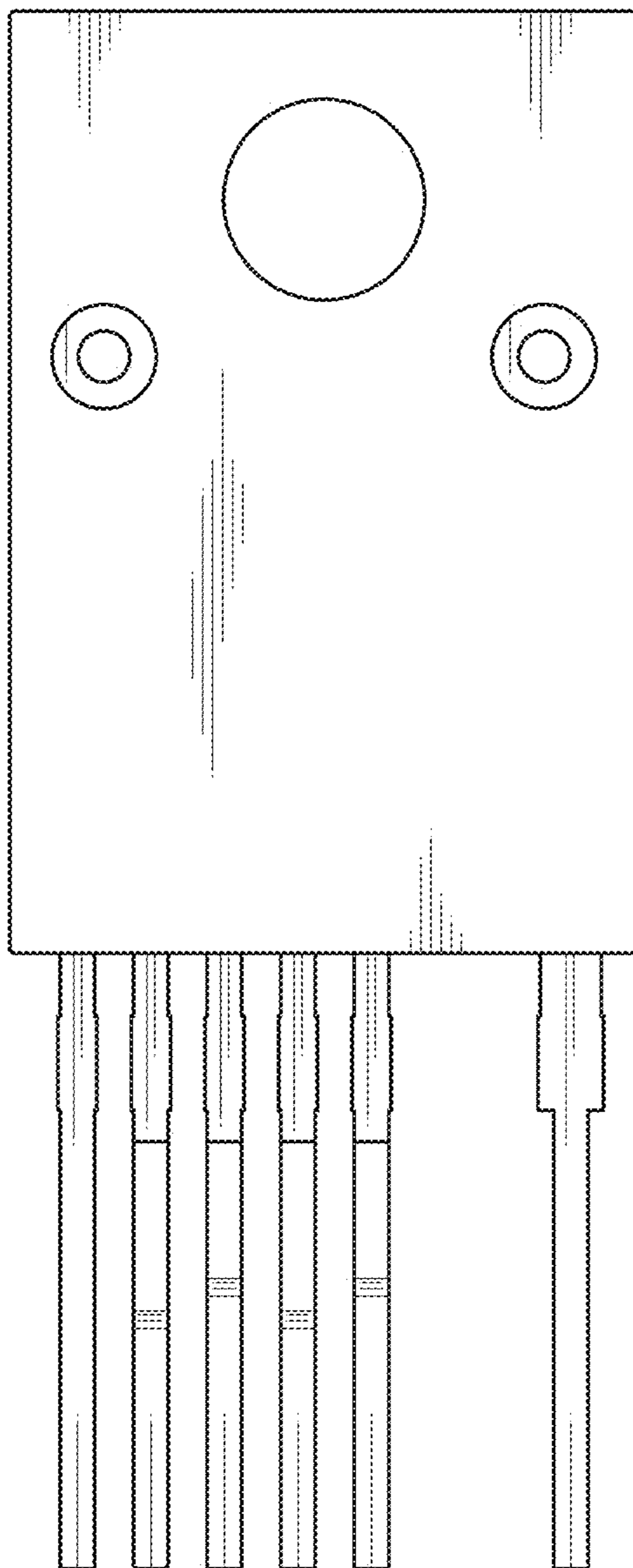


Fig. 4

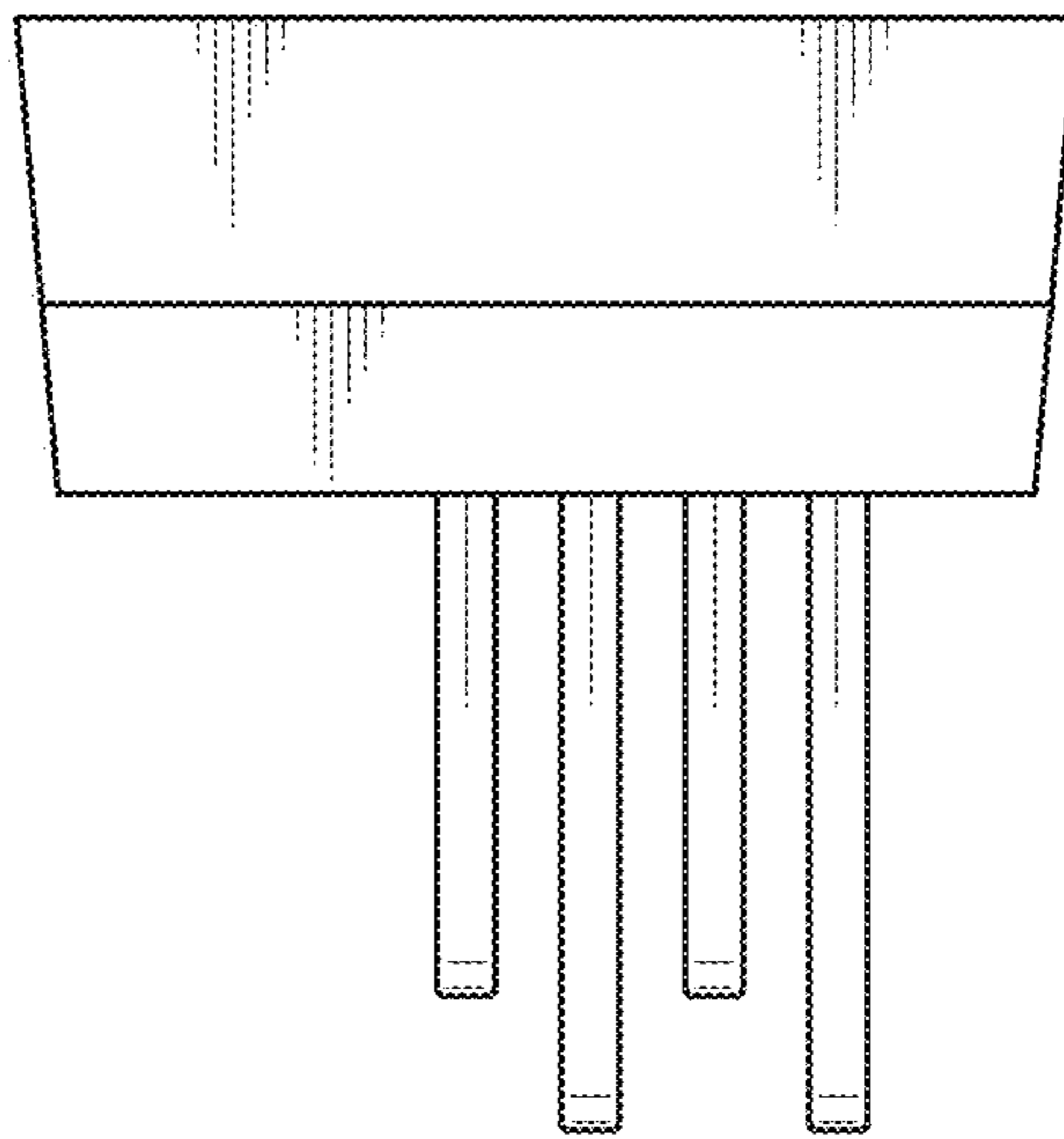


Fig. 5

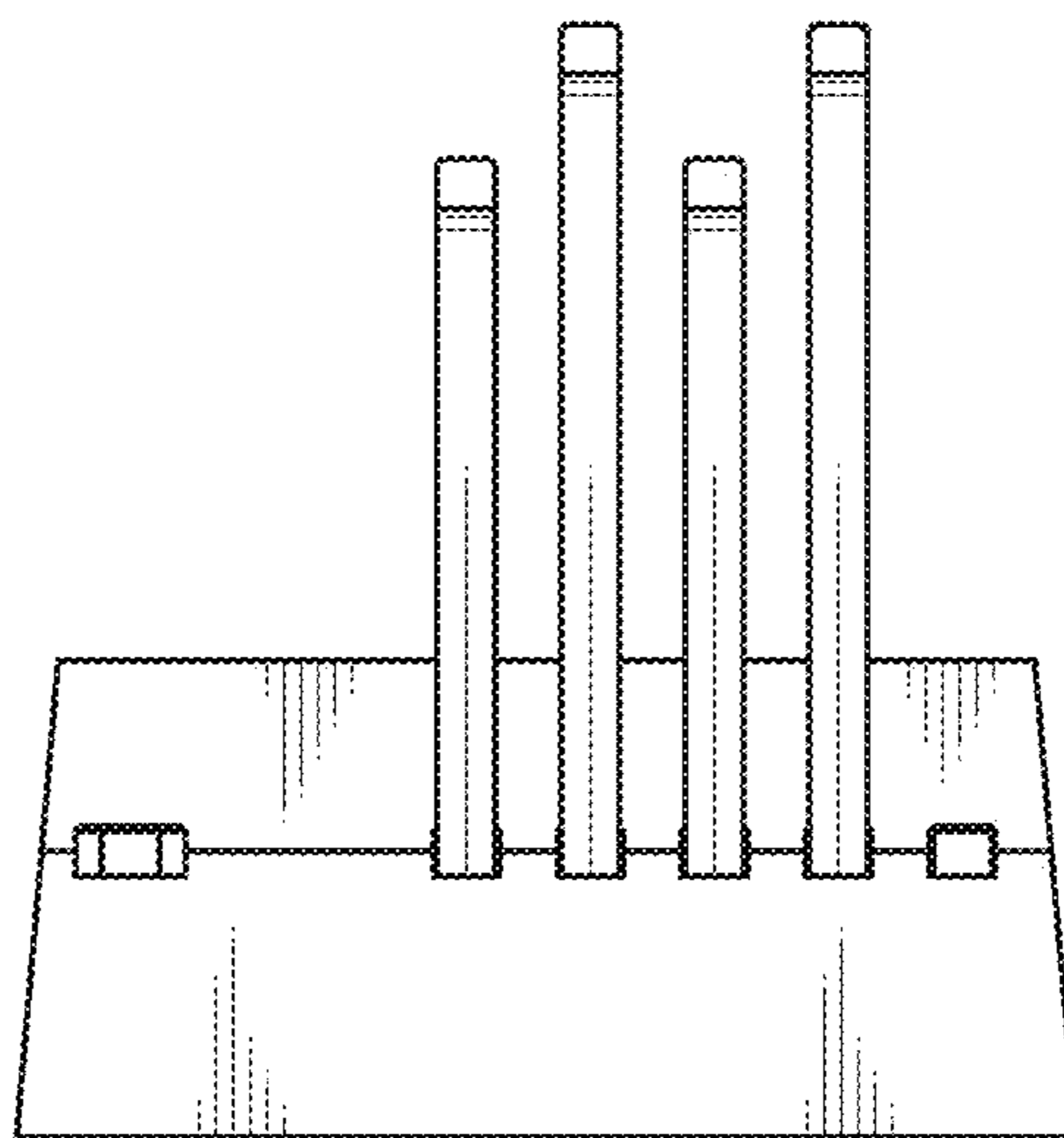


Fig. 6

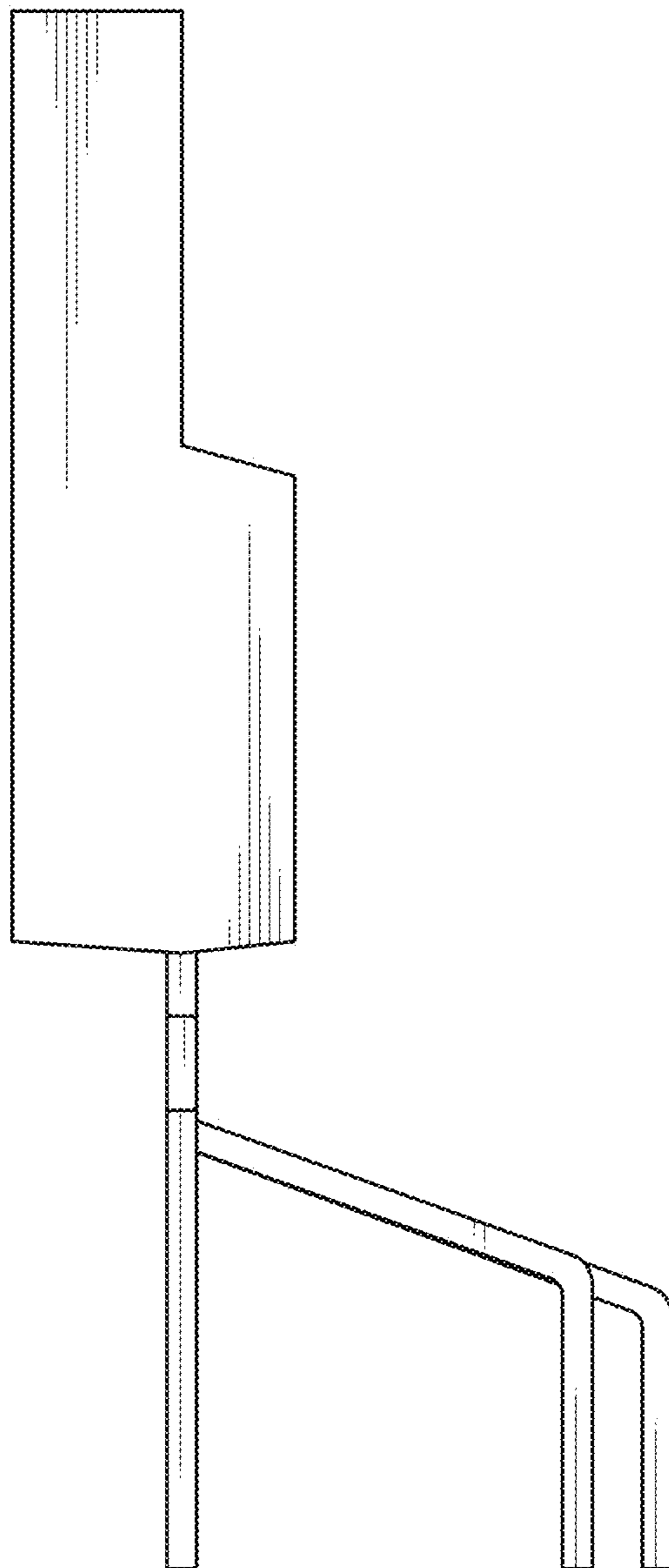


Fig. 7

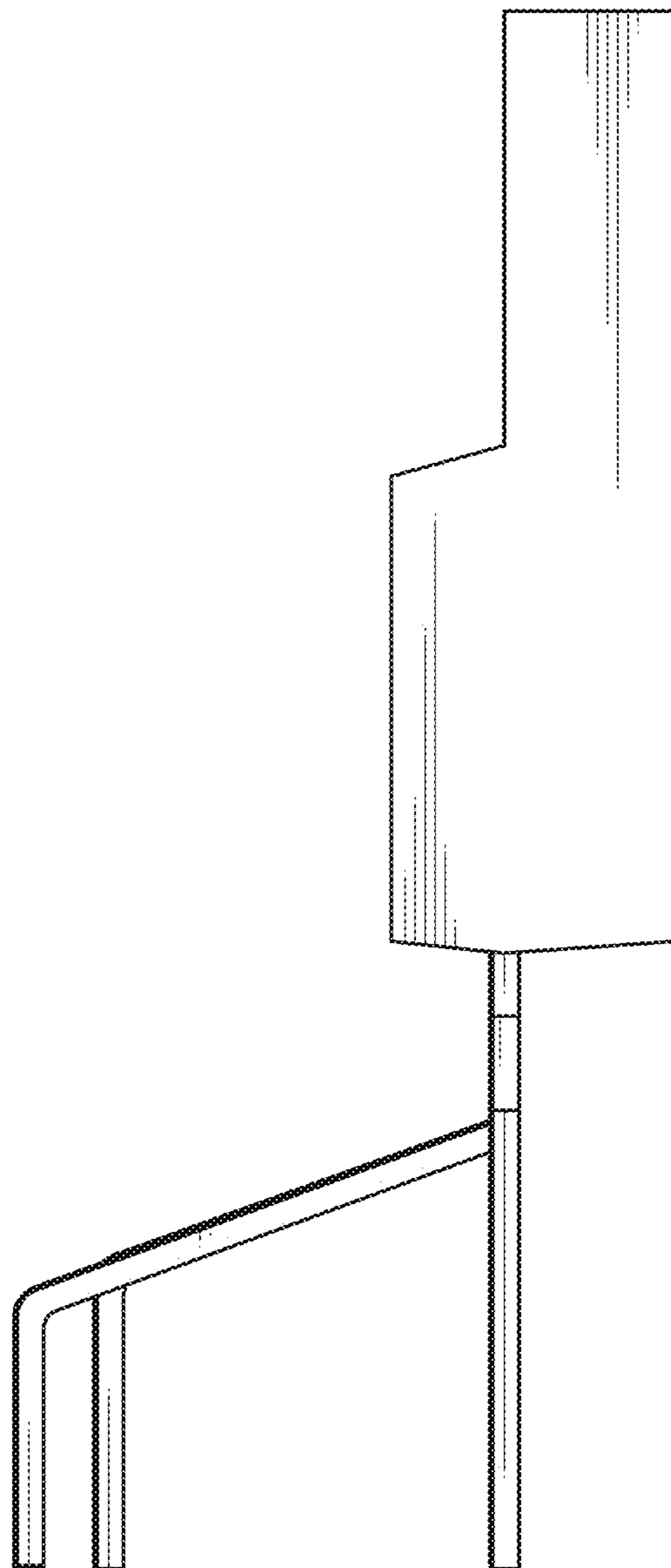




Fig. 8

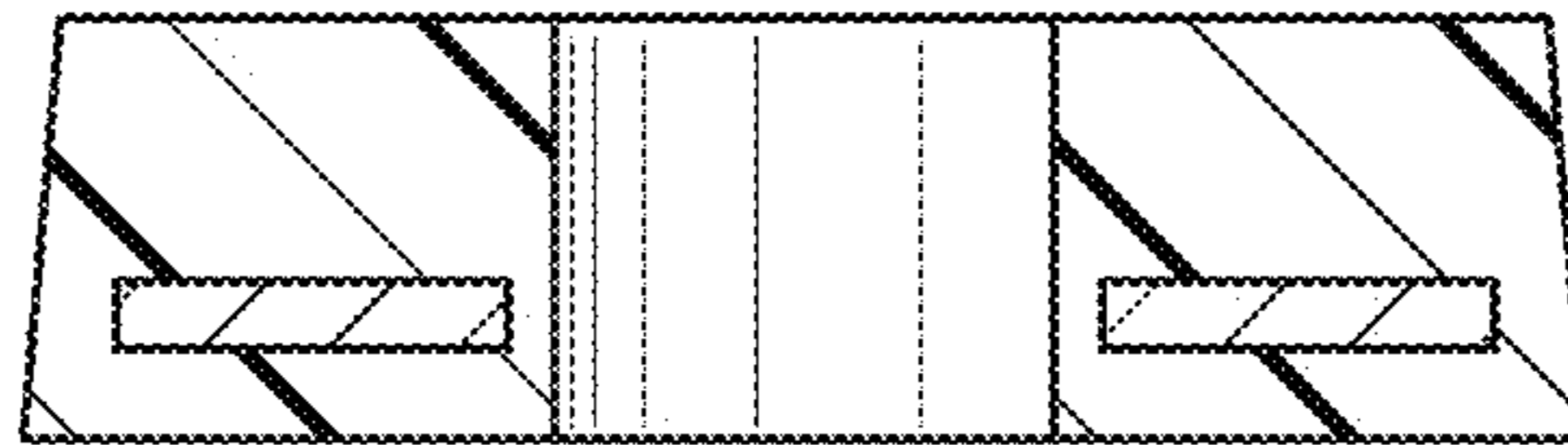


Fig. 9

